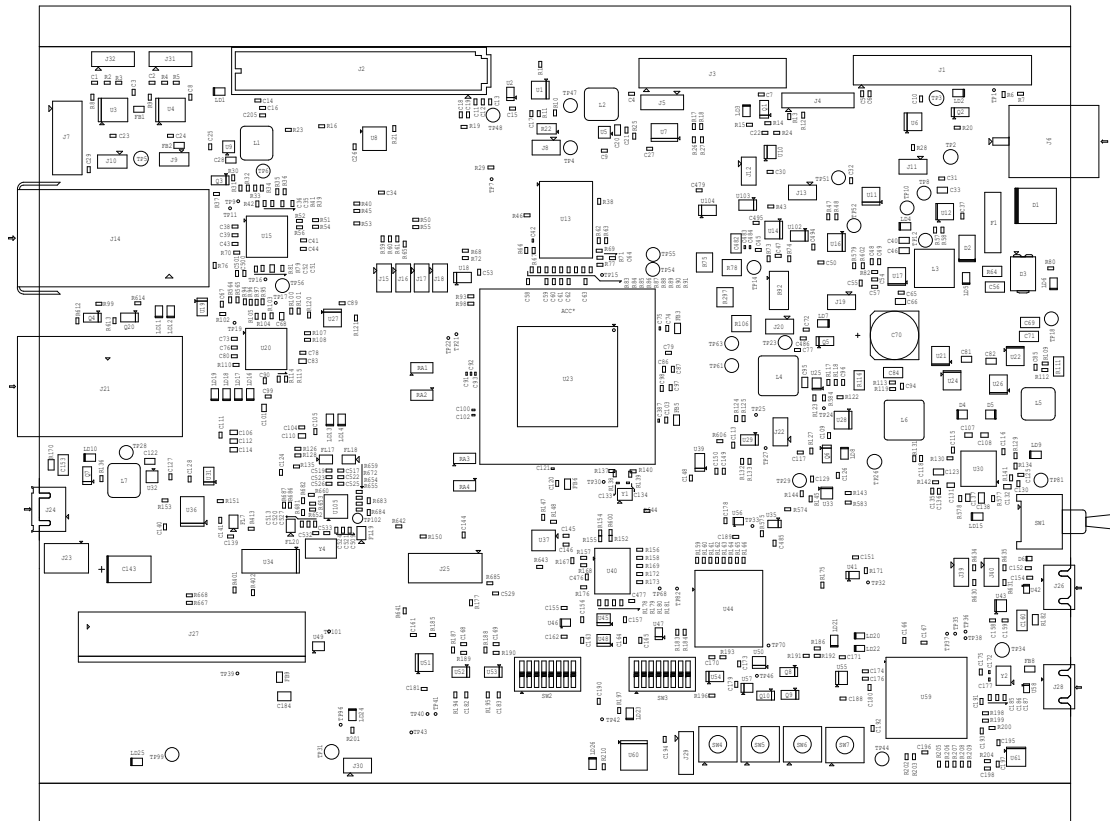



## ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

## PROC101A ASSEMBLY TOP REV A



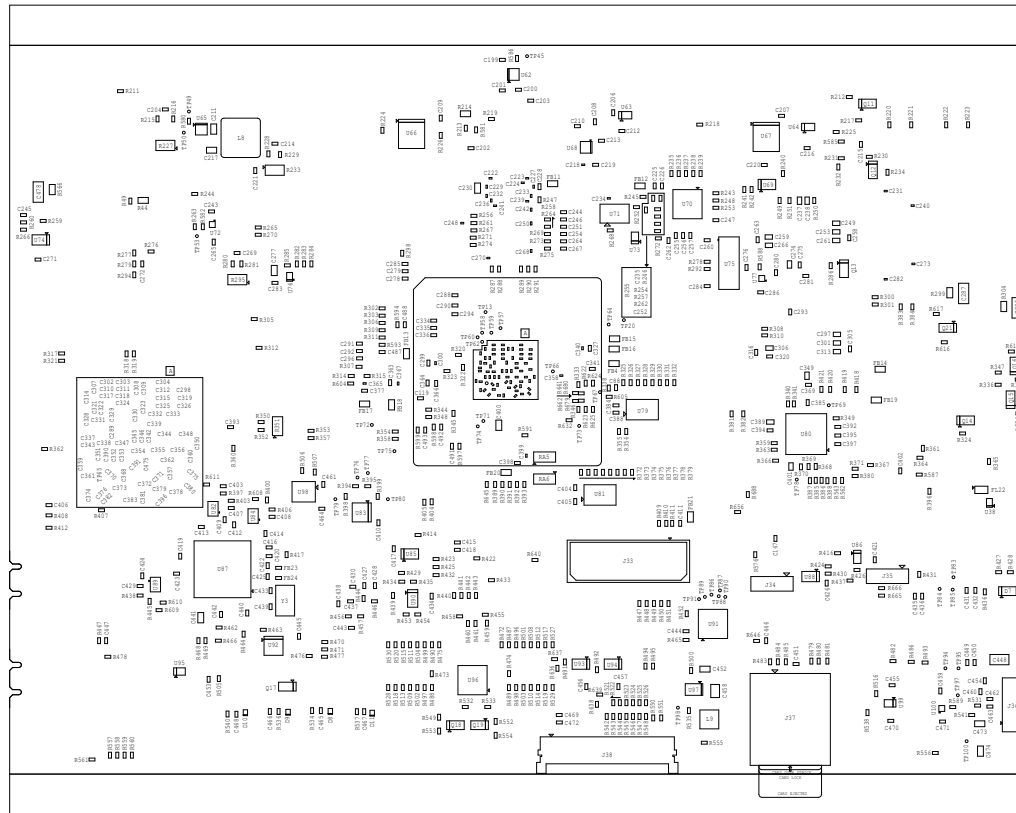
		TEXAS INSTRUMENTS		PROC101A
BOARD NAME: AM64x EVM BOARD		REV: A	DESCRIPTION: TOP ASSEMBLY	
SCALE: 1		DATE: 01/03/21	SHEET 1 OF 2	


# PROC101A ASSEMBLY BOTTOM

## ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not accept
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

## PROC101A ASSEMBLY BOTTOM REV A



		TEXAS INSTRUMENTS		PROC101A
BOARD NAME: AM64x EVM BOARD		REV: A	DESCRIPTION: BOTTOM ASSEMBLY	
SCALE: 1		DATE: 01/03/21	SHEET 2 OF 2	